

ABSTRACT

In accordance with the objectives of the invention a new design and method for the implementation thereof is provided in the form of an "oxide ring". A conventional die is provided with a guard ring or sealing ring, which surrounds and isolates the active surface area of an individual semiconductor die. The "oxide ring" of the invention surrounds the guard ring or sealing ring and forms in this manner a mechanical stress release buffer between the sawing paths of the die and the active surface area of the singulated individual semiconductor die.